In this work, the boriding of binary (Ni–Ti) and ternary (Ni–Ti–Cu) shape memory alloys was carried out in a solid medium at 1173 K for 8 h using the powder pack method with Ekabor-Ni powders. Characterization of boride layer formed on the surface of alloys was identified by optical microscopy and scanning electron microscopy. TiB$_2$, NiB$_2$ and SiC phases in the boride layer of borided binary (Ni–Ti) and ternary (Ni–Ti–Cu) shape memory alloys